PRODUCT CHANGE NOTICE

Alternate Manufacturing Sites for Intersil ZL2005*, ZL2006*, ZL2008*, ZL2105*, and ZL6100* Products

Refer to:
PCN11018

Date: February 11, 2011

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To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Sites for Intersil ZL2005*, ZL2006*, ZL2008, ZL2105*, and ZL6100* Products –** *Jazz Semiconductor Newport Beach, CA and STATS ChipPAC Malaysia*

This notice is to inform you that Intersil is qualifying the Jazz Semiconductor Newport Beach, CA and STATS ChipPAC Malaysia (SCM) facilities as alternate sites for performing wafer fabrication and package assembly of the listed ZL2005*, ZL2006*, ZL2008, ZL2105*, and ZL6100* products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The product and site-specific qualification activities are in progress and scheduled to complete in March 2011.

Products affected:

ZL2005ALNF	ZL2005PALRFT1	ZL2008EALAFT1
ZL2005ALNFT	ZL2006ALNF	ZL2105ALNF
ZL2005ALNFT1	ZL2006ALNFB	ZL2105ALNFT
ZL2005ALNFT1S2568	ZL2006ALNFT	ZL2105ALNFT1
ZL2005ALPF-03	ZL2006ALNFT1	ZL6100ALAF
ZL2005ALPFT-03	ZL2008ALAFT	ZL6100ALAFT
ZL2005ALPFTK-03	ZL2008ALAFT1	ZL6100ALAFTK
ZL2005PALRFT	ZL2008EALAFT	

The Jazz facility is ISO 9001:2008 and ISO/TS 16949:2002 certified and qualified as a supplier to Intersil for wafer fabrication of BCD35 (Bipolar CMOS DMOS) technology products. The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and qualified as a supplier to Intersil for assembly and testing of DFN/QFN packaged products.

There will be no change in the package outline drawing (POD) except for the maximum package height. The maximum package height will change from 0.90mm to 1.00mm with nominal values of 0.85mm and 0.90mm respectively. The 1.00mm maximum aligns with JEDEC POD MO-220 variation V. There will be no change in the moisture sensitivity level (MSL). The qualified material sets and plating combinations are as follows:

Package Style	Material	Current - Amkor	Proposed - SCM
6x6 QFN 36p	Mold Compound	CEL 9220	Sumitomo EME-G770
	Die Attach	AMK06	Ablestik A8290
	Lead Finish	Matte Sn Finish	Matte Sn Finish

The wafer fabrication and assembly qualification plans are designed using JEDEC and other applicable industry standards. A summary of the qualification plan and status of completion is included for reference. The qualification results will be available for review upon completion by request.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM may also be identified by the assembly site code (country of assembly) when marked on the devices. The assembly site code for the SCM facility is "H".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product manufactured at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

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PCN11018

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PCN11018 - Reliability Qualification Plan

Reliability Test	ZL2005 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM	ZL2006 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM	ZL2105 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM	ZL2106 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM
High Temperature Operating Life	NA	SRN100453 Rev 0 0/78 125C 1000hr passed	SRN100432 Rev 0 0/78 125C 1000hr passed	SRN100376 Rev 0 0/78 125C 2000hr passed SRN100376 Rev 1 0/78 125C 2000hr passed SRN100376 Rev 2 0/78 125C 1000hr passed
Biased HAST	NA	NA	NA	SRN100376 Rev 4 0/78 130C, 85%RH PRECOND L2 PBFREE 96hr passed
Storage Life	NA	NA	NA	SRN100376 Rev 0 0/39 150C BAKE AND REFLOW 2000hr passed SRN100376 Rev 1 0/39 150C BAKE AND REFLOW 2000hr passed SRN100376 Rev 2 0/26 150C BAKE AND REFLOW 2000hr passed
Destructive Wire Pull after Storage Life	NA	NA	NA	SRN100376 Rev 0 0/6 passed
Bond Pull Integrity	NA	NA	NA	SRN100376 Rev 0 0/5 175C 96hr completed 2010-11-18 passed SRN100376 Rev 1 0/5 175C 96hr completed 2010-11-18 passed SRN100376 Rev 2 0/5 175C 96hr completed 2011-01-19 passed

Reliability Test	ZL2005 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM	ZL2006 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM	ZL2105 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM	ZL2106 (2.5UM TOP METAL) fab'ed using BCD35 36 LEAD 6X6 QFN at SCM
Moisture Sensitivity Classification	MRT10173 MSL=2@260C (Pb Free) Approved=Yes	MRT10176 MSL=2@260C (Pb Free) Approved=Yes	MRT10174 MSL=2@260C (Pb Free) Approved=Yes	MRT10140 MSL=2@260C (Pb Free) Approved=Yes
Unbiased HAST	SRN100431 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE 96hr passed	SRN100453 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE 96hr passed	SRN100432 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE 96hr passed	SRN100376 Rev 0 0/39 130C, 85%RH PRECOND L2 PBFREE 96hr passed SRN100376 Rev 1 0/39 130C, 85%RH PRECOND L2 PBFREE 96hr passed SRN100376 Rev 2 0/26 130C, 85%RH PRECOND L2 PBFREE 96hr passed
Temperature Cycle	SRN100431 Rev 0 0/81 -65C TO 150C PRECOND L2 PBFREE 500cy passed	SRN100453 Rev 0 0/81 -65C TO 150C PRECOND L2 PBFREE 500cy passed	SRN100432 Rev 0 0/81 -65C TO 150C PRECOND L2 PBFREE 500cy passed	SRN100376 Rev 0 0/39 -65C TO 150C PRECOND L2 PBFREE 500cy passed SRN100376 Rev 1 0/39 -65C TO 150C PRECOND L2 PBFREE 500cy passed SRN100376 Rev 2 0/26 -65C TO 150C PRECOND L2 PBFREE 500cy passed
Destructive Wire Pull after Temp Cycle	NA	NA	NA	SRN100376 Rev 0 0/6 passed
Product Electrical Characterization	Performed by Product Engineering	Performed by Product Engineering	Performed by Product Engineering	Performed by Product Engineering
Statistical Bin Yield Analysis	Performed by Product Engineering	Performed by Product Engineering	Performed by Product Engineering	Performed by Product Engineering
ESD Characterization	HBM 2000V MM 200V CDM 750V	HBM 2000V MM 200V CDM 750V	HBM 2000V MM 200V CDM 750V	HBM 2000V MM 200V CDM 750V
Latch-up Characterization	Passed Class II, LevelA @ 85C	Passed Class II, LevelA @ 85C	Passed Class II, LevelA @ 85C	Passed Class II, LevelA @ 85C